Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A semiconductor device, comprising:

a semiconductor base comprising a first semiconductor region having a first conductivity type, a second semiconductor region having a second conductivity type formed in a specific surface region of said first semiconductor region, and a third semiconductor region having the first conductivity type formed in a specific surface region of said second semiconductor region; and

a first electrode formed-on in a surface region of said second semiconductor region sandwiched between said first semiconductor region and said third semiconductor region, wherein: a first region, in which said third semiconductor region occupies said second semiconductor region at a first rate, is formed at a center of said semiconductor base, and a second region, in which said third semiconductor region occupies said second semiconductor region at a second rate larger than said first rate, is formed at a circumference of said semiconductor base so as to enclose said first region.

- (Original) The semiconductor device according to claim 1, wherein there are a plurality of said third semiconductor region, which are formed to be spaced from each other.
 - 3. (Original) The semiconductor device according to claim 1, wherein said second semiconductor region is formed in a belt shape.
- 4. (Original) The semiconductor device according to claim 3, wherein there are a plurality of said second semiconductor region, which are formed side by side with a space therebetween.
 - 5-6. (Canceled)

7. (Withdrawn) A semiconductor device, comprising a semiconductor base including a first semiconductor region having a first conductivity type, a second semiconductor region having a second conductivity type formed in a surface region of said first semiconductor region, and a third semiconductor region having the first conductivity type formed in a surface region of said second semiconductor region,

wherein said third semiconductor region is formed along a first direction such that a rate at which it occupies said second semiconductor region is larger at a peripheral part of said semiconductor base than at a center part thereof, and formed along a second direction perpendicular to said first direction such that a rate at which said third semiconductor region occupies said second semiconductor region is larger at said peripheral part of said semiconductor base than at said center part thereof.

- 8. (Withdrawn) The semiconductor device according to claim 7, wherein said second semiconductor region is formed in a belt shape, and said first direction is defined in parallel with an extending direction of said second semiconductor region.
- 9. (Withdrawn) The semiconductor device according to claim 7, wherein said second semiconductor region is formed in an island shape, and said first direction is defined in parallel with or perpendicularly to a part of edges of said semiconductor device.
 - 10. (Withdrawn) A semiconductor device, comprising:

a semiconductor base comprising a first semiconductor region having a first conductivity type, a second semiconductor region having a second conductivity type formed in a surface region of said first semiconductor region, and a third semiconductor region having the first conductivity type formed in a surface region of said second semiconductor region;

an insulating film formed on said second semiconductor region sandwiched between said first semiconductor region and said third semiconductor region; and

a first electrode formed on said insulating film,

wherein said insulating film comprises a first region formed at a center region of said semiconductor base to have a first thickness, and a second region formed to have a second

thickness thinner than said first region at a circumference of said semiconductor base so as to enclose said first region.

11. (Withdrawn) A semiconductor device, comprising:

a semiconductor base comprising a first semiconductor region having a first conductivity type, a second semiconductor region having a second conductivity type formed in a surface region of said first semiconductor region, and a third semiconductor region having the first conductivity type formed in a surface region of said second semiconductor region;

an insulating film formed on said second semiconductor region sandwiched between said first semiconductor region and said third semiconductor region; and a first electrode formed on said insulating film,

wherein said second semiconductor region comprises a first region formed at a center of said semiconductor base to have a first impurity concentration, and a second region formed to have a second impurity concentration lower than said first impurity concentration at a circumference of said semiconductor base so as to enclose said first region.